

Fig 1A

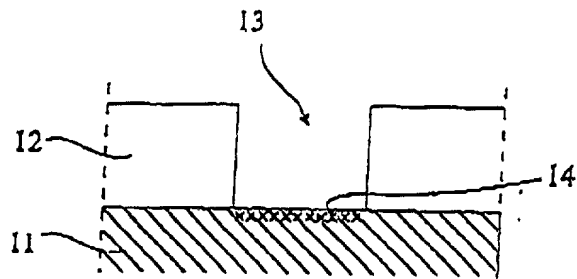


Fig 1B

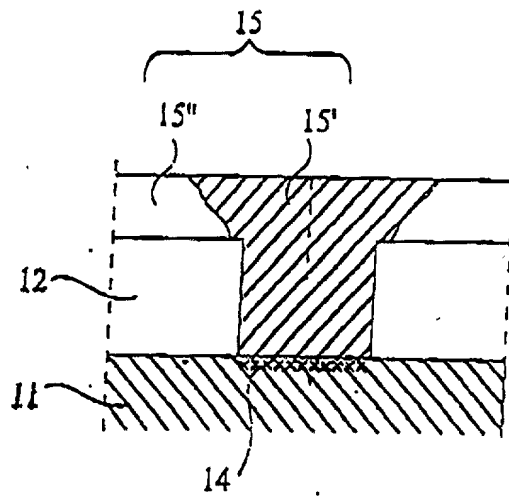


Fig 1C

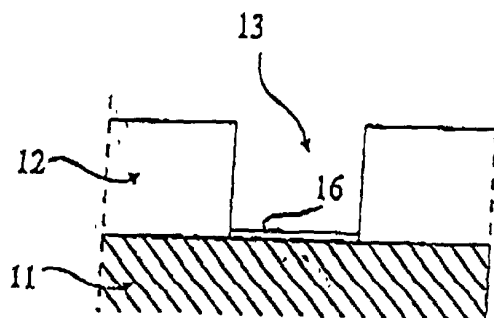


Fig 2A

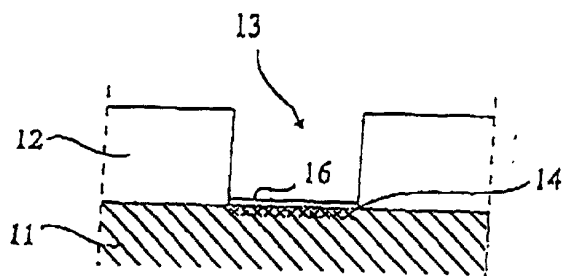


Fig 2B

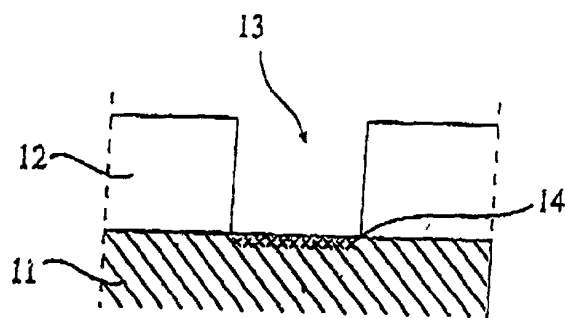


Fig 2C

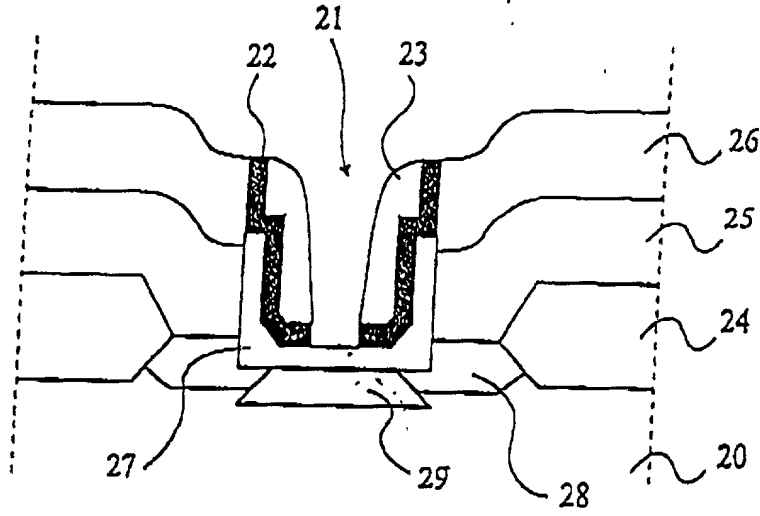


Fig 3A

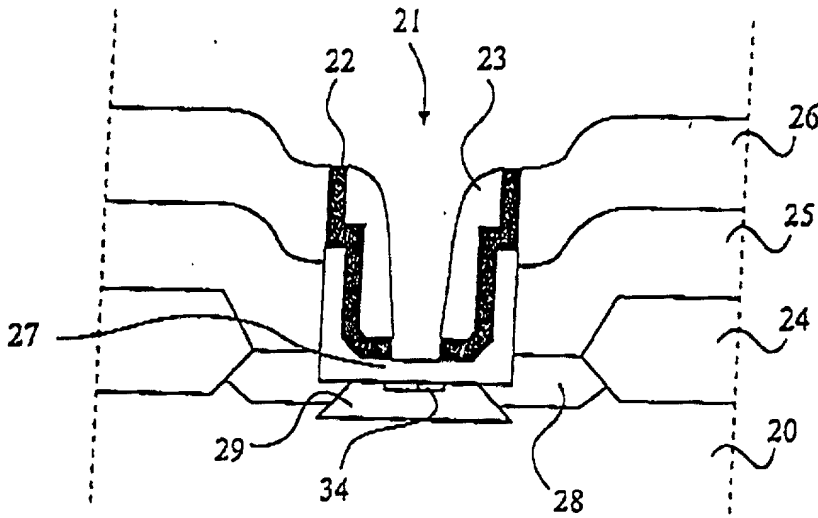


Fig 3B

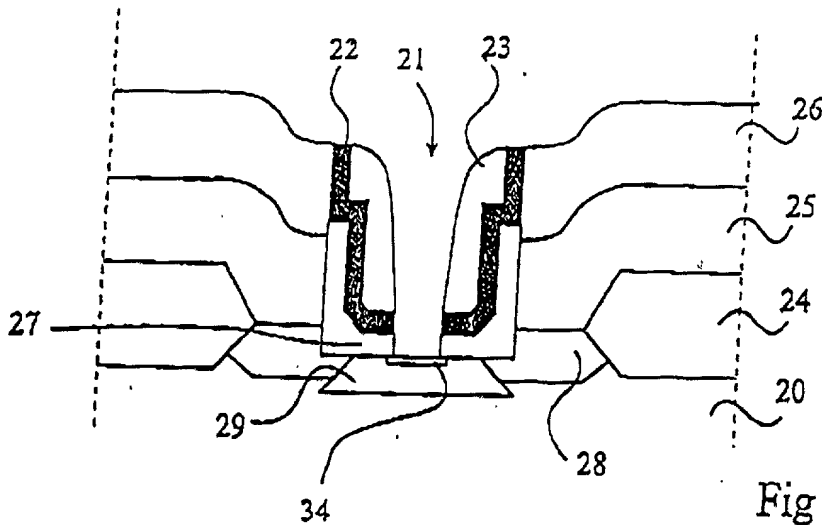


Fig 3C

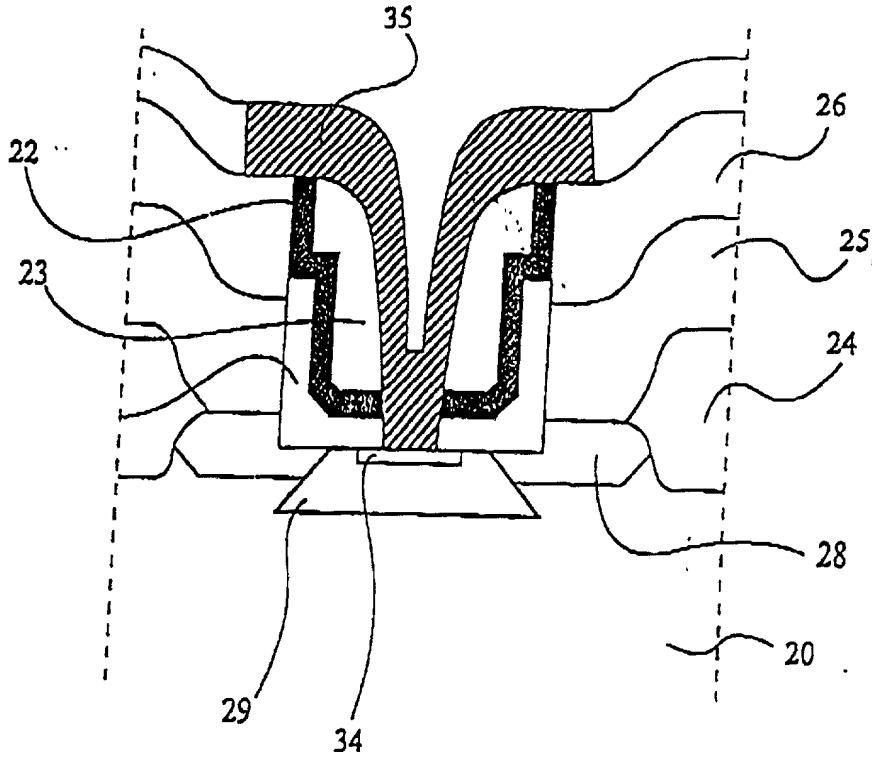


Fig 3D

FIG. 3D is a cross-sectional view of the device 100, showing the internal components and the housing 24. The device 100 includes a central component 23, a housing 24, a top layer 26, a base 28, and a central vertical channel 34. The central component 23 is surrounded by the housing 24, and the top layer 26 is positioned above the housing 24. The base 28 is located at the bottom of the housing 24, and the central vertical channel 34 is formed by the housing 24 and the central component 23. The hatched area 35 is located at the top of the central channel 34. The dashed line 22 is shown on the left side, and the wavy line 20 is shown at the bottom. The label 29 points to the base of the central component 23, and the label 34 points to the central vertical channel 34. The label 35 points to the hatched area 35 at the top of the central channel 34. The label 22 points to the dashed line 22 on the left, and the label 20 points to the wavy line 20 at the bottom.